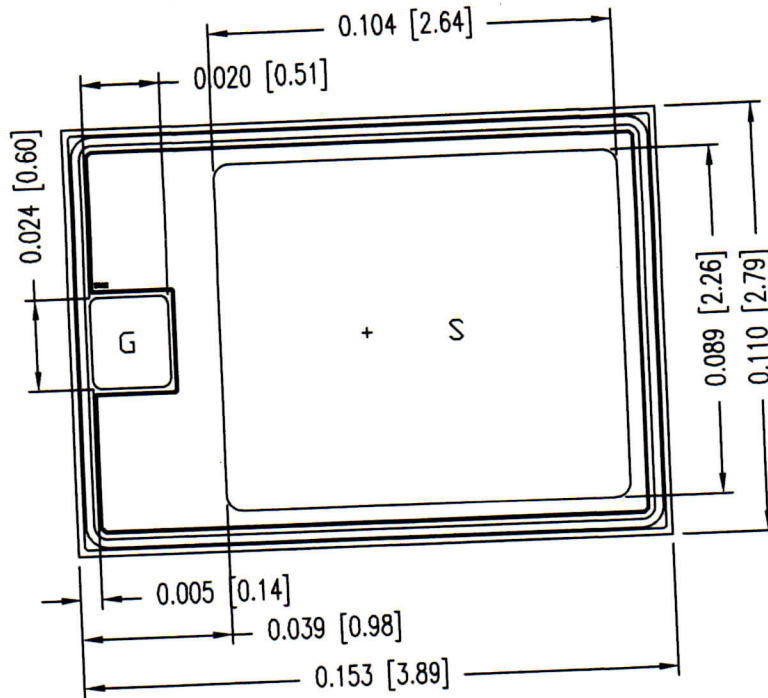




Sierra Components, Inc.

2222 Park Place • Suite 3E • Minden, Nevada 89423
 Phone: 775.783.4940 Fax: 775.783.4947

Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.



Top Material: Al
Backside Material: TiNiAg
Bond Pad Size: G = .020" X .024"
Backside Potential: DRAIN
Mask Ref: IXB9

APPROVED BY: DK

DIE SIZE .110" X .153"

DATE: 4/29/14

MFG: IXYS

THICKNESS .008"

P/N: IXTD26P10T